

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1 – 12 (canceled).

Claim 13 (previously presented). An image-generation device, comprising:

a first printed circuit board for highly complex semiconductors having at least one optical image-recording sensor; and

a second printed circuit board for remaining, less complex components;

a metallic base plate having mounted thereon at least one of said first printed circuit board and said second printed circuit board.

Claim 14 (previously presented). The image-generation device according to claim 13, which comprises an amount of adhesive attaching said at least one printed circuit board to said metallic base plate.

Claim 15 (previously presented). The image-generation device according to claim 13, wherein said highly complex semiconductors include devices selected from the group consisting of microcontrollers and memories, and said less complex components include devices selected from the group consisting of capacitors, transistors, resistors, coils, and plug-in connectors.

Claim 16 (previously presented). The image-generation device according to claim 13, configured for installation in a roof area of a motor vehicle for object detection exterior to and/or interior of the vehicle.

Claim 17 (previously presented). The image-generation device according to claim 13, configured for installation in an exterior rearview mirror of a motor vehicle for detecting an object or for detecting another vehicle on the adjacent lane.

Claim 18 (previously presented). The image-generation device according to claim 13, wherein said first printed circuit board has thermal pads, vias, or Peltier elements.

Claim 19 (previously presented). The image-generation device according to claim 18, wherein said second printed circuit board has thermal pads, vias, or Peltier elements.

Claim 20 (previously presented). The image-generation device according to claim 13, which comprises optics means rigidly located centrally above said optical image-recording sensor.

Claim 21 (previously presented). The image-generation device according to claim 13, wherein said optics means are pre-assembled together with a housing or a retention means.

Claim 22 (currently amended). The image-generation device according to claim 13, wherein said first printed circuit board is a board assembled with at least one of chip-on-board and flip-chip technology.

Claim 23 (currently amended). ~~The~~ An image-generation device according to claim 22, wherein said first printed circuit board has , comprising:

a first printed circuit board for highly complex semiconductors having at least one optical image-recording sensor, said first printed circuit board being a board assembled with at least one of chip-on-board and flip-chip technology and having a plurality of layers for connections and defined impedances;

a second printed circuit board for remaining, less complex components; and

a metallic base plate having mounted thereon at least one of said first printed circuit board and said second printed circuit board.

Claim 24 (currently amended). ~~The image-generation device according to claim 13,~~ An image-generation device, comprising:

a first printed circuit board for highly complex semiconductors having at least one optical image-recording sensor;

a second printed circuit board for remaining, less complex components; and

a metallic base plate having mounted thereon at least one of said first printed circuit board and said second printed circuit board;

wherein said first printed circuit board and said second printed circuit board are located inclined at any angle with respect to one another.

Claim 25 (currently amended). ~~The image-generation device according to claim 13, which comprises~~

An image-generation device, comprising:

a first printed circuit board for highly complex semiconductors having at least one optical image-recording sensor;

a second printed circuit board for remaining, less complex components;

a third printed circuit board having an illuminating unit; and

a metallic base plate having mounted thereon at least one of said first printed circuit board, said second printed circuit board, and said third printed circuit board.

Claim 26 (previously presented). The image-generation device according to claim 25, which further comprises optics means rigidly located above said optical image-recording sensor, and with said third printed circuit board disposed between and/or to the side of said optics means.

Claim 27 (previously presented). The image-generation device according to claim 26, wherein said third printed circuit board is retained by at least one of a housing of said optics means and a separate retention device, with the optics housing and/or the retention device establishing an electrical connection between said illuminating unit and said first printed circuit board.

Claim 28 (previously presented). The image-generation device according to claim 27, wherein said housing of said optics means and/or said retention device has a surface formed with a metal plating defining the electrical connection.

Claim 29 (previously presented). The image-generation device according to claim 25, which comprises a thermal insulating medium disposed between said first printed circuit board and said third printed circuit board.

Claim 30 (previously presented). The image-generation device according to claim 29, wherein said thermal insulating medium is a thermal shield.

Claim 31 (previously presented). The image-generation device according to claim 25, wherein at least one of said second printed circuit board and said third printed circuit board is an FR4 circuit board or a metal circuit board.

Claim 32 (previously presented). The image-generation device according to claim 25, which comprises a plurality of bond wires connecting chip terminals to a respective one of said printed circuit boards and a plurality of bond wires respectively

interconnecting said first printed circuit board, said second printed circuit board, and said third printed circuit board.

Claim 33 (previously presented). The image-generation device according to claim 32, which comprises an amount of sealing compound disposed to protect said bond wires and/or components adjacent thereto from external influences.

Claim 34 (new). An image-generation device, comprising:

a first printed circuit board for highly complex semiconductors having at least one optical image-recording sensor;

a second printed circuit board for remaining, less complex components having a height, away from said second circuit board, greater than a height of said highly complex semiconductors away from said first printed circuit board; and

a common metallic base plate having mounted thereon said first printed circuit board and said second printed circuit board.